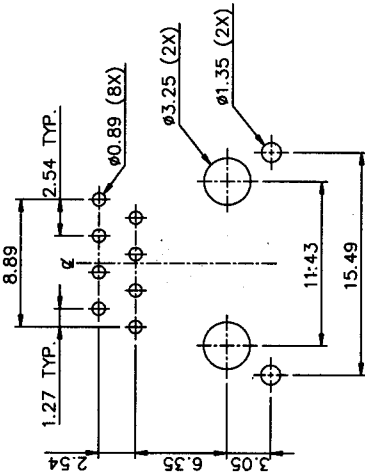
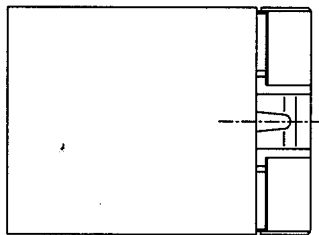
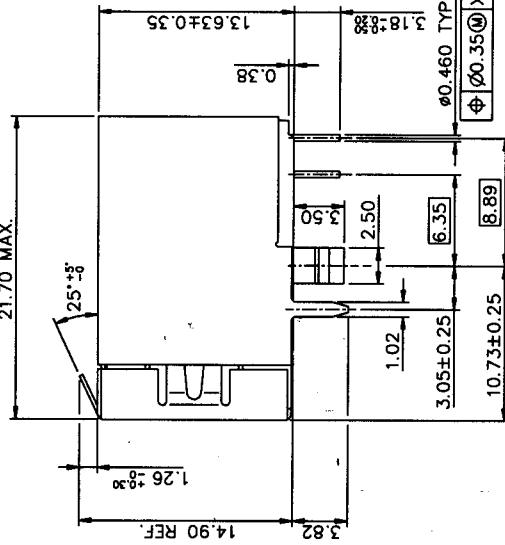
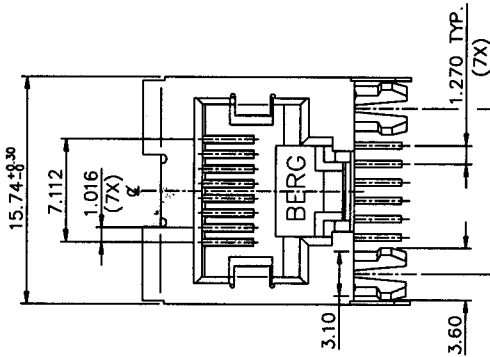


PRODUCT NO.  
74523-00IN  
-00INLE

LEAD FREE PRODUCT NO.



RECOMMENDED PCB LAYOUT



NOTES:

1. RECOMMENDED P.C.B THICKNESS 1.60 MM
2. HOUSING MAT'L: HIGH TEMP RESIN.
3. CONTACTS: PHOS BRONZE ALLOY UNS-C51000, 90.460 ROUND WIRE, PLATING SEE TABLE.
4. SHIELDING MATERIAL: 0.25MM THICK, COPPER ALLOY. SHIELDING PLATING: 30µ" MIN. NICKEL PLATED.
5. PACKAGING: USING TRAY.
6. PART NO. DESCRIPTIONS:  
74523 - X 01 N  
SHIELDING PLATING:  
FOR 30µ" NICKEL PLATING ONLY.  
PORT NUMBERS  
PLATING CODE:  
0=0.76µm/30µ" GXT
7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-00B.
8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
9. IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCJ	
rev	ecr no	dr	date	linear	projection	title	www.fcjconnect.com
A	180318	am	07/21/98	.00 ± 0.15	0.30	R/A CAT 5 MOD JACK 8 POS. SPECIALLY SHIELDED SNAP PEG	
B	103-0443	vl	10/06/03	.000 ± 0.10	± 2'	SPECIALY SHIELDED SNAP PEG	
C	105-0002	ys	07/11/05	angles	unit	product family	M00 JACK
D	105-0018	ys	01/21/05	dr	CA THY LIN12/03/97	size	mm/inch
				engr	TONY CHIEN12/03/97	code	TWN
				chr	TONY CHIEN12/03/97	sheet	1 of 1
				appd	JENN TSAO12/03/97	scale	3 : 1 A.3
sheet	revision	D				74523	
index	sheet	1					

1	4	5	6
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